

MEGIC-00-001



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To: Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572
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#2/I.P.S.
R. Tyson
1/26/01

~~Subject:~~

Serial No. 09/684,519 10/10/00

~~Jin-Yuan Lee~~

~~A THERMALLY COMPLIANT PCB SUBSTRATE
FOR THE APPLICATION OF CHIP SCALE
PACKAGES~~

~~Grp. Art Unit:~~

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

U.S. Patent 6,031,282 to Jones et al., "High Performance
Integrated Circuit Chip Package", discloses an IC package with
an elastomer on a PCB and die pads.

U.S. Patent 5,889,652 to Turturro, "C4-GT Stand Off Rigid
Flex Interposer", discloses a PCB and a substrate with an
elastomer therebetween.

U.S. Patent 6,041,495 to Yoon et al., "Method of Manufacturing a Circuit Board Having Metal Bumps and a Semiconductor Device Package Comprising the Same", discloses a PCB with an elastomer and chip mount.

U.S. Patent 5,990,545 to Schueller et al., "Chip Scale Ball Grid Array for Integrated Circuit Package", discloses a SCBGA with a PCB and direct chip attach with an elastomer to compensate for the thermal mismatch of the PCB and the die.

DiStefano et al., "Designing a Modular Chip-Scale Package Assembly Line", Circuit Assembly, March 1977, (pages not numbered), focuses on the Chip Scale Package (CSP) and provides methods and procedures for relatively easy assembly of CSP's.

Sincerely,

A handwritten signature in black ink, appearing to read 'SBA', with a stylized flourish at the end.

Stephen B. Ackerman,
Reg. No. 37761